

(19) World Intellectual Property
Organization
International Bureau



(43) International Publication Date
30 October 2003 (30.10.2003)

PCT

(10) International Publication Number
WO 2003/090258 A3

(51) International Patent Classification⁷: **H01L 21/66**,
B23K 26/08, 26/40, 26/06

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(21) International Application Number:
PCT/EP2003/004069

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(22) International Filing Date: 17 April 2003 (17.04.2003)

(25) Filing Language: English

(26) Publication Language: English

(30) Priority Data:
S2002/0289 19 April 2002 (19.04.2002) IE
0225033.0 28 October 2002 (28.10.2002) GB

(81) Designated States (*national*): AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NI, NO, NZ, OM, PH, PL, PT, RO, RU, SC, SD, SE, SG, SK, SL, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, YU, ZA, ZM, ZW.

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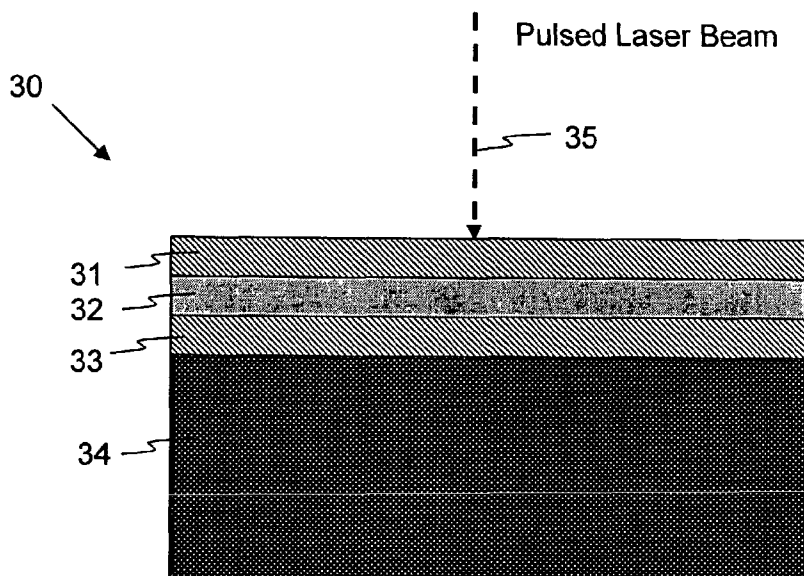
(84) Designated States (*regional*): ARIPO patent (GH, GM, KE, LS, MW, MZ, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian patent (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European patent (AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE, IT, LU, MC, NL, PT, RO, SE, SI, SK, TR), OAPI patent (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).

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[Continued on next page]

(54) Title: LASER MACHINING



(57) Abstract: A substrate (30) is diced using a program-controlled pulsed laser beam (35) apparatus having an associated memory for storing a laser cutting strategy file. The file contains selected combinations of pulse rate Δt , pulse energy density E and pulse spatial overlap to machine a single layer or different types of material in different layers (31, 32, 33, 34) of the substrate while restricting damage to the layers and maximising machining rate to produce die having predetermined die strength and yield. The file also contains data relating to the number of scans necessary using a selected combination to cut through a corresponding layer. The substrate is diced using the selected combinations. Gas handling equipment for inert or active gas may be provided for preventing or inducing chemical reactions at the substrate prior to, during or after dicing.



Published:

- with international search report
- before the expiration of the time limit for amending the claims and to be republished in the event of receipt of amendments

For two-letter codes and other abbreviations, refer to the "Guidance Notes on Codes and Abbreviations" appearing at the beginning of each regular issue of the PCT Gazette.

(88) Date of publication of the international search report:

5 February 2004